IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This level	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfc Information			
upplier Inforn												<u> </u>		
Company name*			Company uni	Company unique ID			Unique ID Authority				Response Date*			
nsemi											2025-07-18			
Contact Name		Title - Contact			I	Phone - Contact*				Email - Contact*				
Product-Env-Stewa	ards		Product Enviro Compliance]	NA				Product-Env-Stewards@onsemi.com			
authorized Represe	entative*	Title - Representative			I	Phone - Representative*				Email - Representative*				
Product-Env-Stewards Produ			Product Envi	Product Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requesto	er Item Number	Mfr Item Number Mfr Item Name NCP189CMTWADJT NCP189 AD slew 1 AG		Mfr Item Name			Effective Date	Versio	n	Manufacturing Site	1	Weight*	UOM	Unit Type
				rate ADJ WDFNW6	5 2x2	2025-07-18 MY1		MY1	ç	0.38	mg	Each		
Ianufacturing	Proccess Informatio	n												
Terminal Plating / Grid Array Material Terminal			erminal Base A	ninal Base Alloy J-STD-020 MSL Ratin			Peak Process Body Temperature Max Time at Peak				Temperat	ure Numb	per of Reflow Cyc	eles
Matte Tin (Sn) - annealed			CU Alloy 1		1		260	260 C 30		30	seconds 3			
omments														
vel 1 - maximum t	ime at peak temperature	during sol	dering is 10-3	0 seconds										
or more informati	on regarding material cor	nposition r	please refer to	page 3		-						_		

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight 0.46	Unit of Measure	
Die	0.46	mg	Supplier	Silicon (Si)	7440-21-3			mg	
Die Attach	0.23	mg		Epoxy resin	proprietary data		0.0345	mg	
			Supplier	Silver (Ag)	7440-22-4		0.184	mg	
			Supplier	Bismaleimide	13676-54-5		0.0115	mg	
Lead Frame	2.7	mg	Supplier	Silver (Ag)	7440-22-4		0.0462	mg	
			Supplier	Tin (Sn)	7440-31-5		0.1618	mg	
			Supplier	Zinc (Zn)	7440-66-6		0.0051	mg	
			Supplier	Chromium (Cr)	7440-47-3		0.0076	mg	
			Supplier	Copper (Cu)	7440-50-8		2.4729	mg	
Mold Compound-Black	5.54	mg	Supplier	Silica Amorphous (SiO2)	7631-86-9		0.4155	mg	
			Supplier	Carbon Black (C)	1333-86-4		0.0277	mg	
			Supplier	Fused Silica (SiO2)	60676-86-0		4.4043	mg	
			Supplier	EpoxyNovolaCresins (Cresolic)	64425-89-4		0.277	mg	
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.4155	mg	
Plating	0.4	mg	Supplier	Tin (Sn)	7440-31-5		0.4	mg	
Wire Bond - Cu	0.05	mg	Supplier	Palladium (Pd)	7440-05-3		0.001	mg	
			Supplier	Copper (Cu)	7440-50-8		0.049	mg	